Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	11799	ball near10 grid near10 array	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 15:51
L2	8551	1 and (solder with (bump ball))	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 15:51
L3	4024	2 and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 15:51
L4	3524	3 and wir$3	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 15:51
L5	7391	ball near10 grid near10 array	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:51
L6	3076	5 and (solder and (bump ball))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:51
L7	522	6 and resin	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:51
L8	269	7 and wir$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:52
L9	22693	(solder near5 (bump ball))	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 16:09
L10	21582	L9 and (substrate wafer chip die)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 16:09
L11	3849	L10 and (conduct$3 near5 trace)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 16:10
L12	2925	L11 and (encapsulat$3 resin polymer)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 16:10
L13	1679	L12 and (ball near5 grid)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 16:09
L14	873	L13 and (dic$3 singulat$3 saw$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 16:09

L15	15489	(solder near5 (bump ball))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:09
L17	191	L15 and (conduct$3 near5 trace)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:10
L18	73	L17 and (encapsulat$3 resin polymer)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:11